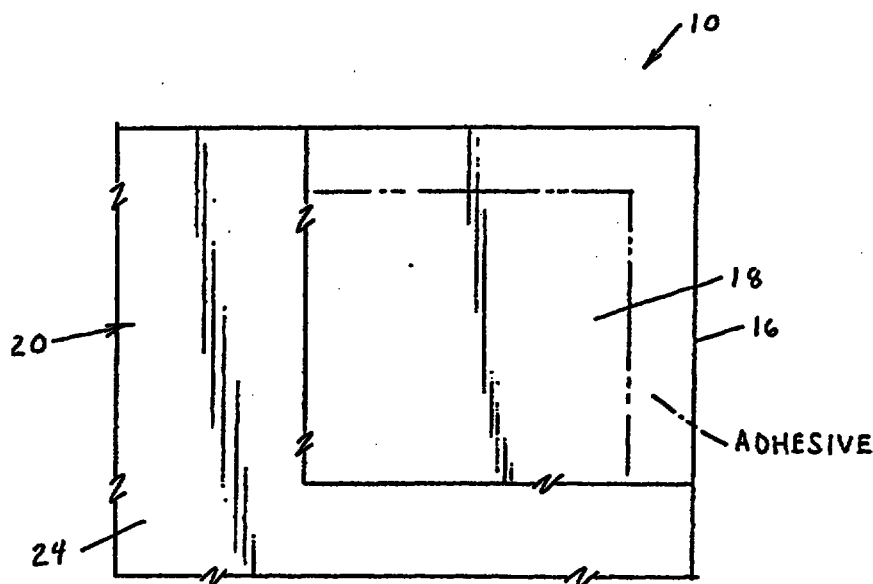




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(54) Title: COMPONENT OF PRINTED CIRCUIT BOARDS



(57) Abstract

A component (10) for use in manufacturing articles, such as printed circuit boards, comprising a laminate constructed of a sheet of copper foil (20) that, in a finished circuit board, constitutes a functional element, and a sheet of carbon steel (14) having a layer of an inert metal (16) thereon, the sheet of carbon steel (14) constituting a discardable element. One surface (22) of the copper sheet (20) and the surface (18) of the inert metal layer (16) on the carbon steel sheet (14) are essentially uncontaminated and engageable with each other at interfaces. The copper sheet (20) is attached to the inert metal layer (16) of the carbon steel (14) at their borders and defines substantially uncontaminated central zones inwardly of the edges of the sheets that are unjoined at the interfaces.